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Field Device Integration (FDI) - Part 1: Overview

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 07/23

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Supersedes EN IEC 62769-1:2021

English Version

**Field Device Integration (FDI®) - Part 1: Overview
(IEC 62769-1:2023)**

Intégration des appareils de terrain (FDI®) - Partie 1: Vue
d'ensemble
(IEC 62769-1:2023)

Feldgeräteintegration (FDI®) - Teil 1: Überblick
(IEC 62769-1:2023)

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EN IEC 62769-1:2023 (E)**European foreword**

The text of document 65E/854/CDV, future edition 3 of IEC 62769-1, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-1:2023.

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 62453-1 NOTE Approved as EN 62453-1

IEC 62443 (series) NOTE Approved as EN IEC 62443 (series)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

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NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804	series	Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804	series
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 61804-4	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 4: EDD interpretation	EN IEC 61804-4	-
IEC 62453	series	Field device tool (FDT) interface specification	EN 62453	series
IEC 62541	series	OPC Unified Architecture	EN IEC 62541	series
IEC/TR 62541-1	-	OPC Unified Architecture - Part 1: Overview CLC and concepts	IEC/TR 62541-1	-
IEC 62541-3	-	OPC Unified Architecture - Part 3: Address Space Model	EN IEC 62541-3	-
IEC 62541-4	-	OPC Unified Architecture - Part 4: Services	EN IEC 62541-4	-
IEC 62541-5	-	OPC Unified Architecture - Part 5: Information Model	EN IEC 62541-5	-
IEC 62541-100	-	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	-
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	-	-
IEC 62769-3	-	Field Device Integration (FDI®) - Part 3: Server	-	-
IEC 62769-4	2023	Field Device Integration (FDI®) - Part 4: FDI Packages	-	-

EN IEC 62769-1:2023 (E)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62769-5	2023	Field Device Integration (FDI®) - Part 5: FDI Information Model	-	-
IEC 62769-6	2023	Field Device Integration (FDI®) - Part 6: FDI Technology Mappings	-	-
IEC 62769-7	-	Field Device Integration (FDI®) - Part 7: Communication Devices	-	-
IEC 62769-8	-	Field device integration (FDI®) - Part 8:EDD to OPC-UA Mapping	-	-
ISO/IEC 11578	-	Information technology - Open Systems Interconnection - Remote Procedure Call (RPC)	-	-



IEC 62769-1

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INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI®) –
Part 1: Overview**

**Intégration des appareils de terrain (FDI®) –
Partie 1: Vue d'ensemble**





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IEC 62769-1

Edition 3.0 2023-04

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Field device integration (FDI®) –
Part 1: Overview**

**Intégration des appareils de terrain (FDI®) –
Partie 1: Vue d'ensemble**

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FIELD DEVICE INTEGRATION (FDI®) –

Part 1: Overview

FOREWORD

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IEC 62769-1 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added references to Part 6-100 and Part 6-200 (technology mapping for .NET and HTML5);
- b) updated Subclause 8.3.1: major version, minor version and revision shall be written as two-digit numbers;
- c) added reference to new Part 8 and FDI® OPC UA Server Facet.

The text of this International Standard is based on the following documents:

Draft	Report on voting
65E/854/CDV	65E/927/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts in the IEC 62769 series, published under the general title *Field device integration (FDI)*[®], can be found on the IEC website.

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FIELD DEVICE INTEGRATION (FDI®) –

Part 1: Overview

1 Scope

This part of IEC 62769 describes the concepts and overview of the Field Device Integration (FDI®¹) specifications. The detailed motivation for the creation of this technology is also described (see 4.1). Reading this document is helpful to understand the other parts of this multi-part standard.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

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IEC 62453 (all parts), *Field device tool (FDT) interface specification*

IEC 62541 (all parts), *OPC Unified Architecture*

IEC TR 62541-1, *OPC Unified Architecture – Part 1: Overview and concepts*

IEC 62541-3, *OPC Unified Architecture – Part 3: Address Space Model*

IEC 62541-4, *OPC Unified Architecture – Part 4: Services*

IEC 62541-5, *OPC Unified Architecture – Part 5: Information Model*

IEC 62541-100, *OPC Unified Architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI®) – Part 2: Client*

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IEC 62769-6:2023, *Field Device Integration (FDI®) – Part 6: FDI® Technology Mappings*

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koniec náhľadu – text ďalej pokračuje v platenej verzii STN